1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Low $Q_r$ and low $I_{RM}$
- Low leakage current
- High power capability due to clip-bonding technology
- Small and flat lead SMD power plastic package

3. Applications

- High efficiency DC-to-DC conversion
- LED lighting
- Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- OR-ing

4. Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{F(AV)}$</td>
<td>average forward current</td>
<td>$\delta = 0.5; f = 20 \text{ kHz}; \text{square wave}; T_{sp} \leq 167 ^\circ \text{C}$</td>
<td>-</td>
<td>-</td>
<td>20</td>
<td>A</td>
</tr>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td>$T_J = 25 ^\circ \text{C}$</td>
<td>-</td>
<td>-</td>
<td>100</td>
<td>V</td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 20 \text{ A}; \text{pulsed}; T_J = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>775</td>
<td>840</td>
<td>mV</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 100 \text{ V}; \text{pulsed}; T_J = 25 ^\circ \text{C}$</td>
<td>[1]</td>
<td>1.5</td>
<td>10</td>
<td>$\mu\text{A}$</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 100 \text{ V}; \text{pulsed}; T_J = 125 ^\circ \text{C}$</td>
<td>[1]</td>
<td>2.5</td>
<td>10</td>
<td>mA</td>
</tr>
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</table>

[1] Very short pulse, in order to maintain a stable junction temperature.
5. Pinning information

Table 2. Pinning information

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
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<tr>
<td>1</td>
<td>A</td>
<td>anode</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>A</td>
<td>anode</td>
<td></td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>K</td>
<td>cathode</td>
<td></td>
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6. Ordering information

Table 3. Ordering information

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<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Name</th>
<th>Description</th>
<th>Version</th>
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</thead>
<tbody>
<tr>
<td>PMEG100T200ELPE</td>
<td>CFP15B</td>
<td>plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body</td>
<td>SOT1289B</td>
<td></td>
</tr>
</tbody>
</table>

7. Marking

Table 4. Marking codes

<table>
<thead>
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<th>Type number</th>
<th>Marking code</th>
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<tbody>
<tr>
<td>PMEG100T200ELPE</td>
<td>100T</td>
</tr>
<tr>
<td></td>
<td>L20E</td>
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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_R</td>
<td>reverse voltage</td>
<td>T_j = 25 °C</td>
<td>-</td>
<td>100</td>
<td>V</td>
</tr>
<tr>
<td>I_F</td>
<td>forward current</td>
<td>δ = 1; T_sp ≤ 165 °C</td>
<td>-</td>
<td>28.2</td>
<td>A</td>
</tr>
<tr>
<td>I_F(AV)</td>
<td>average forward current</td>
<td>δ = 0.5; f = 20 kHz; square wave; T_sp ≤ 167 °C</td>
<td>-</td>
<td>20</td>
<td>A</td>
</tr>
<tr>
<td>I_FSM</td>
<td>non-repetitive peak current</td>
<td>t_p = 8.3 ms; half sine wave; T_j(θ) = 25 °C</td>
<td>-</td>
<td>260</td>
<td>A</td>
</tr>
<tr>
<td>P_tot</td>
<td>total power dissipation</td>
<td>T_amb ≤ 25 °C</td>
<td>[1]</td>
<td>1.66</td>
<td>W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[2]</td>
<td>2.15</td>
<td>W</td>
</tr>
<tr>
<td>T_j</td>
<td>junction temperature</td>
<td></td>
<td>-</td>
<td>175</td>
<td>°C</td>
</tr>
<tr>
<td>T_amb</td>
<td>ambient temperature</td>
<td></td>
<td>-55</td>
<td>175</td>
<td>°C</td>
</tr>
<tr>
<td>T_stg</td>
<td>storage temperature</td>
<td></td>
<td>-65</td>
<td>175</td>
<td>°C</td>
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</table>


9. Thermal characteristics

Table 6. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$R_{th(j-a)}$</td>
<td>thermal resistance from junction to ambient</td>
<td>in free air</td>
<td>[1]</td>
<td>[2]</td>
<td>90</td>
<td>K/W</td>
</tr>
<tr>
<td>$R_{th(j-sp)}$</td>
<td>thermal resistance from junction to solder point</td>
<td>[3]</td>
<td>70</td>
<td></td>
<td></td>
<td>K/W</td>
</tr>
</tbody>
</table>

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses $P_R$ are a significant part of the total power losses.


---

**Fig. 1.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

---

**Fig. 2.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
## 10. Characteristics

### Table 7. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{(BR)R}$</td>
<td>reverse breakdown voltage</td>
<td>$I_R = 1 \text{ mA}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>100</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 1 \text{ A}; \text{pulsed}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>430</td>
<td>505</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 5 \text{ A}; \text{pulsed}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>540</td>
<td>620</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 10 \text{ A}; \text{pulsed}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>640</td>
<td>720</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 15 \text{ A}; \text{pulsed}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>720</td>
<td>800</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 20 \text{ A}; \text{pulsed}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>775</td>
<td>840</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 20 \text{ A}; \text{pulsed}; T_j = -40 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>775</td>
<td>840</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 20 \text{ A}; \text{pulsed}; T_j = 125 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>655</td>
<td>725</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 60 \text{ V}; \text{pulsed}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>0.6</td>
<td>3.6</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 100 \text{ V}; \text{pulsed}; T_j = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>1.5</td>
<td>10</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 100 \text{ V}; \text{pulsed}; T_j = 125 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>2.5</td>
<td>10</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 100 \text{ V}; \text{pulsed}; T_j = 150 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>-</td>
<td>9.5</td>
<td>48</td>
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<tr>
<td>$C_d$</td>
<td>diode capacitance</td>
<td>$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>1600</td>
<td>-</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>-</td>
<td>450</td>
<td>-</td>
</tr>
<tr>
<td>$t_{rr}$</td>
<td>reverse recovery time</td>
<td>$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R\text{meas}} = 0.1 \text{ A}; T_j = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>55</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td></td>
<td></td>
<td>ramp recovery</td>
<td>$dl_F/dt = 200 \text{ A/µs}; I_F = 6 \text{ A}; V_R = 26 \text{ V}; T_j = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>18</td>
<td>-</td>
</tr>
<tr>
<td>$I_{RM}$</td>
<td>peak reverse recovery current</td>
<td>-</td>
<td>1.8</td>
<td>-</td>
<td>A</td>
<td></td>
</tr>
<tr>
<td>$Q_{rr}$</td>
<td>reverse recovery charge</td>
<td>-</td>
<td>23</td>
<td>-</td>
<td>nC</td>
<td></td>
</tr>
<tr>
<td>$V_{FRM}$</td>
<td>peak forward recovery voltage</td>
<td>$I_F = 0.5 \text{ A}; dl_F/dt = 20 \text{ A/µs}; T_j = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>410</td>
<td>-</td>
<td>mV</td>
</tr>
</tbody>
</table>

[1] Very short pulse, in order to maintain a stable junction temperature.
### Fig. 3. Forward current as a function of forward voltage; typical values

- **Pulsed condition**
  - (1) $T_j = 175 ^\circ C$
  - (2) $T_j = 150 ^\circ C$
  - (3) $T_j = 125 ^\circ C$
  - (4) $T_j = 100 ^\circ C$
  - (5) $T_j = 85 ^\circ C$
  - (6) $T_j = 25 ^\circ C$
  - (7) $T_j = -40 ^\circ C$

### Fig. 4. Reverse current as a function of reverse voltage; typical values

- **Pulsed condition**
  - (1) $T_j = 175 ^\circ C$
  - (2) $T_j = 150 ^\circ C$
  - (3) $T_j = 125 ^\circ C$
  - (4) $T_j = 100 ^\circ C$
  - (5) $T_j = 85 ^\circ C$
  - (6) $T_j = 25 ^\circ C$
  - (7) $T_j = -40 ^\circ C$

### Fig. 5. Diode capacitance as a function of reverse voltage; typical values

- $f = 1 \text{ MHz}$; $T_{\text{amb}} = 25 ^\circ C$

### Fig. 6. Average forward power dissipation as a function of average forward current; typical values

- $T_j = 100 ^\circ C$
  - (1) $\delta = 0.1$
  - (2) $\delta = 0.2$
  - (3) $\delta = 0.5$
  - (4) $\delta = 0.8$
  - (5) $\delta = 1$; DC
**Fig. 7.** Average reverse power dissipation as a function of reverse voltage; typical values

\[ P_{R(AV)} (W) \]

- \( T_j = 100 \, ^\circ C \)
- (1) \( \delta = 1; \) DC
- (2) \( \delta = 0.9 \)
- (3) \( \delta = 0.8 \)
- (4) \( \delta = 0.5 \)
- (5) \( \delta = 0.2 \)

**Fig. 8.** Average forward current as a function of ambient temperature; typical values

\[ I_{F(AV)} (A) \]

- \( T_j = 175 \, ^\circ C \)
- (1) \( \delta = 1; \) DC
- (2) \( \delta = 0.5; f = 20 \, kHz \)
- (3) \( \delta = 0.2; f = 20 \, kHz \)
- (4) \( \delta = 0.1; f = 20 \, kHz \)

**FR4 PCB, standard footprint**

*Fig. 9.** Average forward current as a function of ambient temperature; typical values

\[ I_{F(AV)} (A) \]

- \( T_j = 175 \, ^\circ C \)
- (1) \( \delta = 1; \) DC
- (2) \( \delta = 0.5; f = 20 \, kHz \)
- (3) \( \delta = 0.2; f = 20 \, kHz \)
- (4) \( \delta = 0.1; f = 20 \, kHz \)

**Fig. 10.** Average forward current as a function of solder point temperature; typical values

\[ I_{F(AV)} (A) \]

- \( T_j = 175 \, ^\circ C \)
- (1) \( \delta = 1; \) DC
- (2) \( \delta = 0.5; f = 20 \, kHz \)
- (3) \( \delta = 0.2; f = 20 \, kHz \)
- (4) \( \delta = 0.1; f = 20 \, kHz \)
100 V, 20 A low leakage current Trench MEGA Schottky barrier rectifier

FR4 PCB, standard footprint
$R_{th} = 90 \text{ K/W}$

Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values

FR4 PCB, mounting pad for cathode 1 cm$^2$
$R_{th} = 70 \text{ K/W}$

Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values

Soldering point of cathode tab
$R_{th} = 7 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values
11. Test information

![Diagram of reverse recovery definition; step recovery](image1)

**Fig. 14. Reverse recovery definition; step recovery**

![Diagram of reverse recovery definition; ramp recovery](image2)

**Fig. 15. Reverse recovery definition; ramp recovery**

![Diagram of forward recovery definition](image3)

**Fig. 16. Forward recovery definition**
Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: \( I_{(AV)} = I_M \times \delta \) with \( I_M \) defined as peak current, \( I_{RMS} = I_{(AV)} \) at DC, and \( I_{RMS} = I_M \times \sqrt{\delta} \) with \( I_{RMS} \) defined as RMS current.

12. Package outline

Fig. 18. Package outline CFP15B (SOT1289B)
13. Soldering

Footprint information for reflow soldering of CFP15B package

SOT1289B

Fig. 19. Reflow soldering footprint for CFP15B (SOT1289B)
14. Revision history

Table 8. Revision history

<table>
<thead>
<tr>
<th>Data sheet ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
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<td>PMEG100T200ELPE v.1</td>
<td>20210927</td>
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</tbody>
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15. Legal information

Data sheet status

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<th>Document status</th>
<th>Product status</th>
<th>Definition</th>
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<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
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<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
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<td>This document contains the product specification.</td>
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</table>

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term "short data sheet" is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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